

WHAT IS CLAIMED IS:

1. A wiring board comprising:

an electronic component; and

an embedding resin having a dielectric constant of less than or equal to about 5 and $\tan\delta$ of less than or equal to about 0.08,

wherein, said electronic component is embedded in said embedding resin.
2. The wiring board according to claim 1, wherein said embedding resin comprises carbon black in an amount of less than or equal to about 1.4 mass%.
3. The wiring board according to claim 1, wherein said embedding resin comprises a thermosetting resin as a resin component and at least one inorganic filler.
4. The wiring board according to claim 3, wherein said thermosetting resin is at least one of a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, or a cresol-novolak-type epoxy resin.
5. The wiring board according to claim 1, wherein said embedding resin assumes a color having a base color tone of black, blue, green, red, orange, yellow, or violet.
6. The wiring board according to claim 1, further comprising:

a substrate, including a build-up layer formed by laminating an insulating layer and a wiring layer in alternate fashion, formed on at least one surface of a core substrate; and

an opening formed so as to penetrate at least one of said core substrate and said build-up layer,

wherein said electronic component is placed in the opening and embedded by means of said embedding resin.

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